

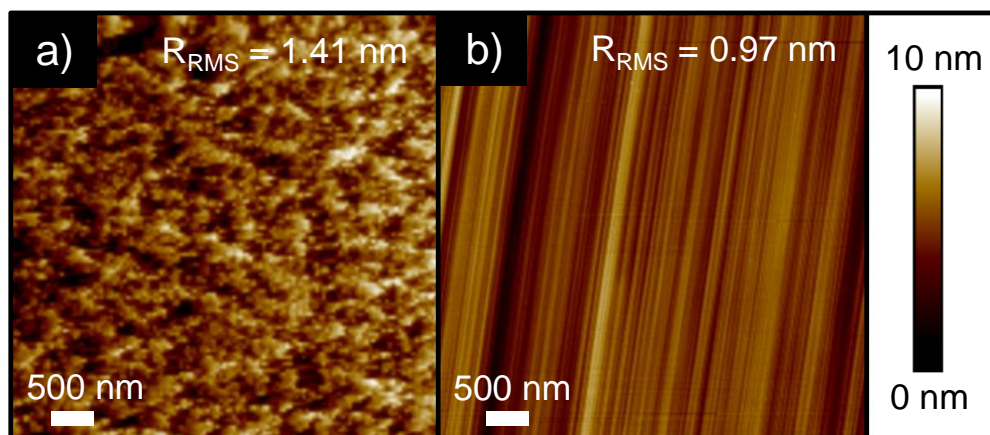
# Selective Area Growth of GaN Nanowires and Nanofins by Molecular Beam Epitaxy on Heteroepitaxial Diamond (001) Substrates - Supporting Information

Florian Pantle,\* Fabian Becker, Max Kraut, Simon Wörle, Theresa Hoffmann, Sabrina Artmeier, and Martin Stutzmann\*

*Walter Schottky Institut and Physics Department, Technische Universität München, Am Coulombwall 4, 85748 Garching, Germany*

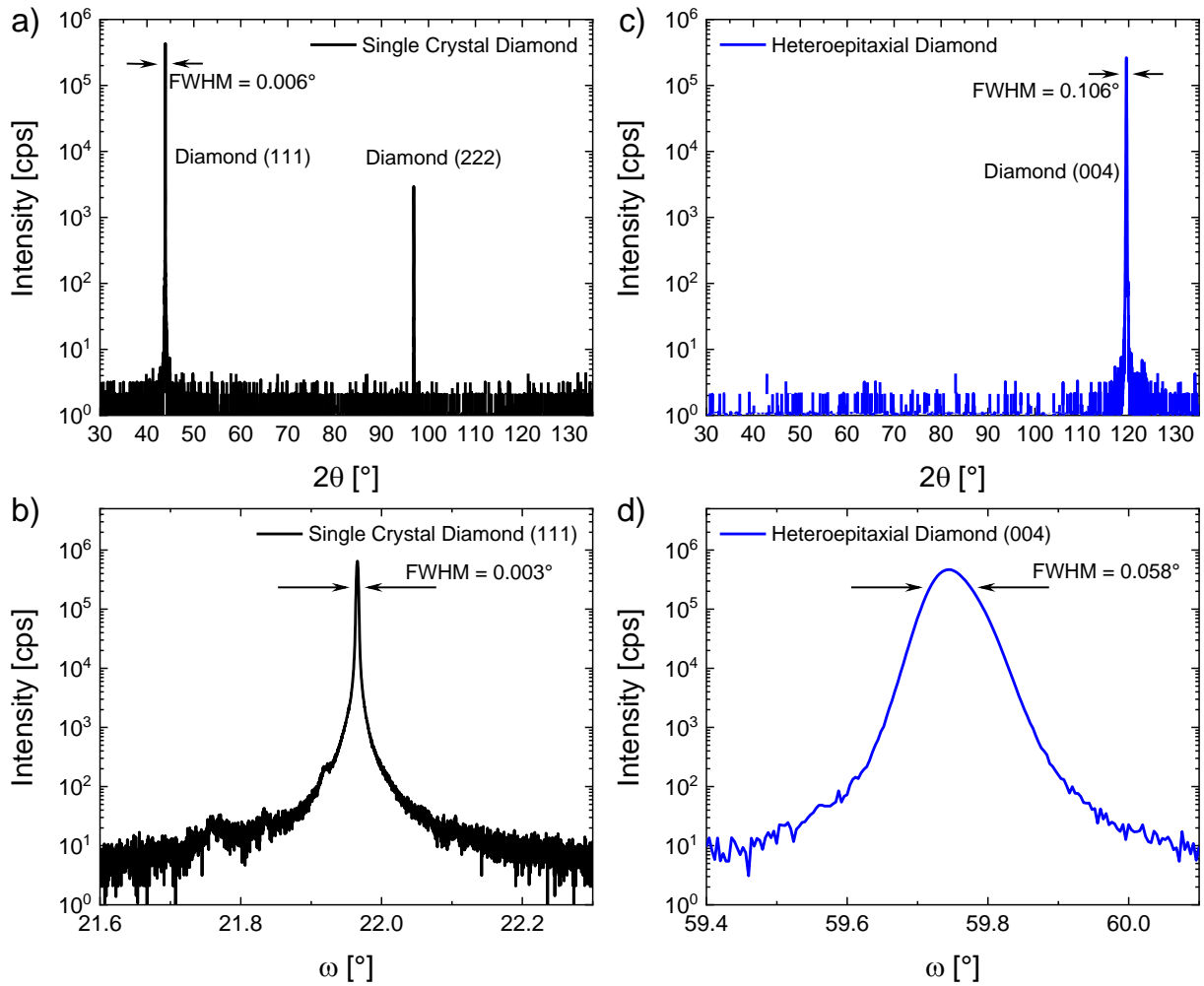
E-mail: florian.pantle@wsi.tum.de; stutz@wsi.tum.de

## Diamond Substrates



**Figure S1:** AFM images of the diamond substrates: a) SCD (111) and b) HD (001).

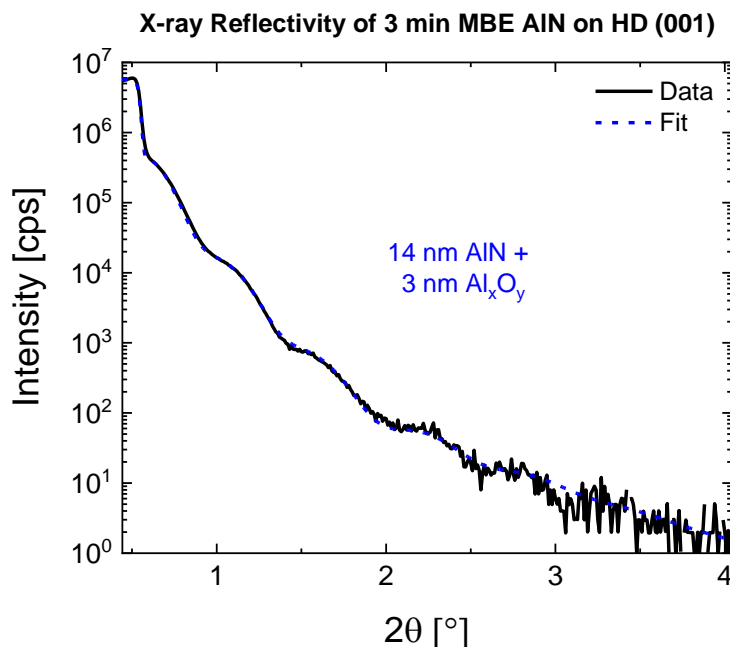
Figure S1 depicts  $5 \times 5 \mu\text{m}^2$  AFM images of the diamond substrates. The surface of the SCD (111) (Fig. S1a) shows a structuring with an RMS roughness of 1.41 nm. This morphology is a consequence of prior multiple recycling the SCD for several GaN NW growth runs and the following cleaning of the diamond surface via etching the sample in hot KOH, O-plasma treatments and  $\text{H}_2\text{O}_2/\text{HF}$  solutions. The less expensive HD substrates were used only once. The structure visible in Figure S1b) is due to the polishing of the HD (001) surface, which results in an RMS roughness of 0.97 nm. These polishing grooves are along the [100] diamond axis.



**Figure S2:** High resolution XRD of the diamond substrates: a)  $2\theta/\omega$ -scan and b)  $\omega$ -rocking curve of the SCD (111), c)  $2\theta/\omega$ -scan and d)  $\omega$ -rocking curve of a HD (001).

Figure S2 shows high resolution XRD data of the diamond substrates used. In Figure S2a), the diamond (111) and (222) reflexes are at a  $2\theta$ -angle of  $43.93^\circ$  and  $96.87^\circ$ , respectively. The  $\omega$ -rocking curve of the SCD (111) reflex (Fig. S2b) has a FWHM of  $0.003^\circ$ . Figure S2c) shows the  $2\theta/\omega$ -scan of a HD (001) with the diamond (004) reflex at  $119.49^\circ$ . The  $\omega$ -rocking curve of the HD (004) reflex (Fig. S2d) has a FWHM of  $0.106^\circ$ .

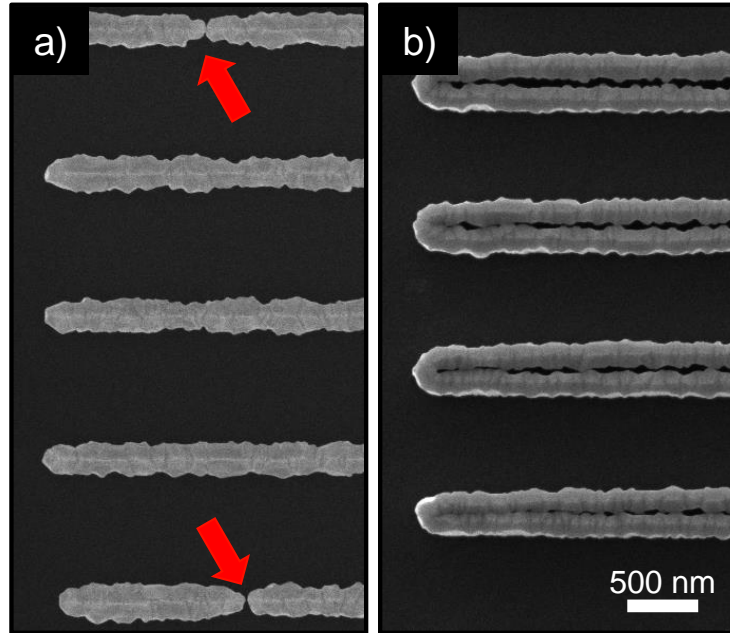
## AlN Buffer Thickness



**Figure S3:** X-ray reflectivity data (black curve) of an AlN buffer on HD (001) grown for 3 min. A fit (dashed blue curve) for which a native surface oxide is assumed estimates an AlN thickness of approx. 14 nm with a surface oxide thickness of approx. 3 nm.

In Figure S3, the X-ray reflectivity data of an AlN buffer layer grown for 3 min is shown. The blue dashed line depicts a fit, which assumes a native surface oxide on top of the AlN. Using this model, an AlN thickness of approx. 14 nm with a native surface oxide thickness of approx. 3 nm was determined.

## Lithographic Limits

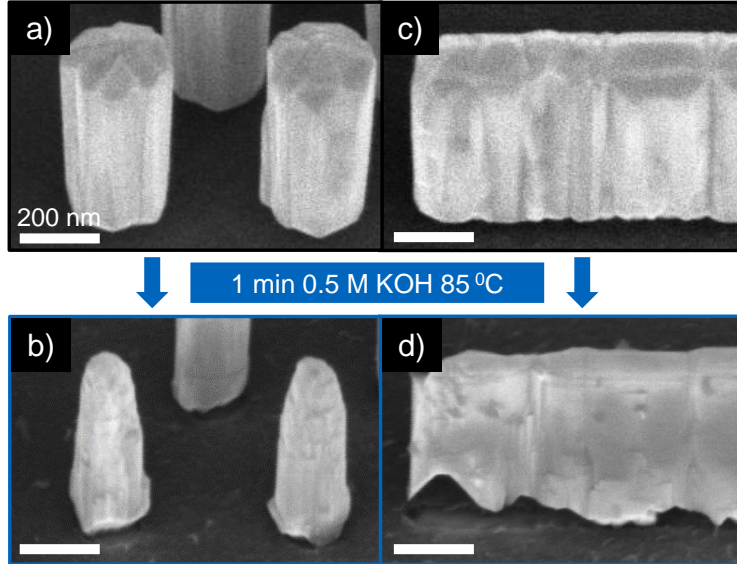


**Figure S4:** Top view SEM images of GaN NFs on AlN-buffered HD (001) at the lithographic process limits: a) Thin NFs and b) thick NFs.

Figure S4 shows the limitations of the GaN NF thickness variation on AlN-buffered HD (001). Too small exposure doses during electron beam lithography result in non-continuous slits in the Ti mask. This leads to breaks in the NFs, which are marked by the red arrows in Figure S4a). In contrast, too high doses result in an overexposure of the electron beam resist. This hinders the resist lift-off in the middle of the nano-slit. Consequently, the thickest NFs split up in a double fin (Fig. S4b).

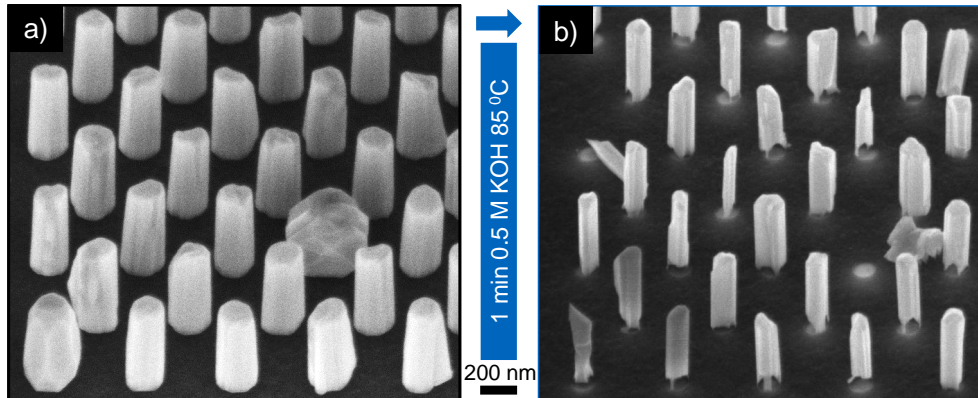
## Polarity of GaN NSs

In Figure S5 GaN NSs on AlN-buffered HD (001) before and after polarity-selective KOH etching at 85°C for 1 min are shown. The height of the NSs decreased by approx. 40 nm and the average NS width by almost 100 nm. Further, an under-etching of the GaN NFs is observed, whereas the GaN NWs are only slightly attacked by the etchant at the bottom.



**Figure S5:** SEM images of GaN NWs and NFs grown on AlN-buffered HD (001) a), c) before and b), d) after etching with 0.5 M KOH at 85°C for 1 min.

Figures S6a) and b) show GaN NWs on bare HD (001) before and after etching for 1 min.



**Figure S6:** SEM images of GaN NWs on bare HD (001) a) before and b) after etching with 0.5 M KOH at 85°C for 1 min.

The etched NWs are thinner but not significantly shorter. A lateral etch rate of approx. 40 nm/min has been determined. Moreover, all NWs show signs of etching at the bottom.